

GP Component

REV.
A0

ECN NO.

LOCATIONS

DESCRIPTION
Initial

DATE
2015/11/02

DESIGN
Phebe Su

The technical drawing includes several key components:

- Top View:** Shows overall dimensions such as length (77.3 ± 0.2), width ($\phi 1.35 \pm 0.05$), and pin pitch ($0.6X35=21.00$). It also indicates features like "C OF TWO POST" and various reference points.
- SECTIONAL A-A:** A cross-sectional view showing contact areas, solder area, and dimensions like 0.5 ± 0.10 and 0.8 .
- B-B:** Another sectional view focusing on different parts of the component's profile.
- RECOMMENDED PCB LAYOUT:** Provides detailed placement guidelines for pins (PIN1, PIN2, PIN203, PIN204) and dimensions relative to the board edges.
- MATING AND UNMATING INSTRUCTIONS:** Includes numbered steps (1-7) and a diagram illustrating how to correctly insert or remove the module from its socket.

NOTES:

- MATERIAL:**
 - 1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0; COLOR: BLACK.
 - 1.2 CONTACTS: COPPER ALLOY
 - 1.3 LATCH: STAINLESS STEEL
 - 1.4 NUT: STAINLESS STEEL
 - 1.5 FLOATING PEG: COPPER ALLOY
- FINISH:**
 - 2.1 CONTACT: GOLD (SEE TABLE) PLATED ON CONTACT AREA AND GOLD 2u" SOLDER AREA. 50u" MIN. NICKEL UNDERPLATING.
 - 2.2 FLOATING PEG: 100u" MIN. MATTE-TIN. 50u" MIN. NICKEL UNDERPLATING.
- REFLOW SOLDER CAPABLE TO 260°C.
- SHOULD BE MEASURED BY CPK
- MAKED "DIMENSIONS NEED BE CONTROLLED IN FAI."

PART NUMBER:
MDDR3-204XX10

Series number

PLATING CODE:

1: GOLD FLASH 4: Au15u"
2: Au5u" 5: Au20u"
3: Au10u" 6: Au30u"

MARK & HSG COLOR:

0: DDR3 STD 1.5V & BLACK
1: DDR3 STD & BLACK 2: STD & BLACK
3: DDR3 STD 1.5V & IVORY
4: DDR3 STD & IVORY 5: STD & IVORY

PIN NUMBER CODE:
204: 204 PINS

NO	VARIETY	QTY	MATERIA	REMARK
	Matrix Electronics Co.,Ltd			
TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR3 SO DIMM 8.OH STD ASSY
		CHECKED BY: Vicky Hsieh	DATE : 2015/11/02	PART NO. : MDDR3-204XX10
UNIT: mm [inch]		APPROVED BY1: Richard Hsieh	DATE : 2015/11/02	MOLD NO. : NA
SCALE:1:1 SIZE:A4		APPROVED BY2: Richard Hsieh	DATE : 2015/11/02	DRAW NO. :
				SHEET NO. : 1 OF 2

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/11/02	Phebe Su

UPPER CONTACT
(CONTACT AREA)

LOWER CONTACT
(CONTACT AREA)

0.8 (32)
(SOLDER AREA)

4.5±0.10 (30) 4.5±0.10 (31)

SECTIONAL A-A
SCALE 2:1

4.30 (20)

3.00 (21)

12.00 (22)
2PLC

0.20 (27)

0.85 (24)
2PLC

0.2+0.1 / -0.05 (25)

0.10 (26)

ALL CONTACT TAILS AND PEGS

EXTRACTION

UP

MATED

ROCK

UNMATE

④

⑦

NOTES:

- MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0; COLOR: BLACK.
 - CONTACTS: COPPER ALLOY
 - LATCH: STAINLESS STEEL
 - NUT: STAINLESS STEEL
 - FLOATING PEG: COPPER ALLOY
- FINISH:
 - CONTACT:
GOLD (SEE TABLE) PLATED ON CONTACT AREA AND GOLD 2u"
SOLDER AREA. 50u" MIN. NICKEL UNDERPLATING.
 - FLOATING PEG:
100u" MIN. MATTE-TIN. 50u"MIN. NICKEL UNDERPLATING.
- REFLOW SOLDER CAPABLE TO 260°C.
- △ SHOULD BE MEASURED BY CPK
- MAKED "⊕" DIMENSIONS NEED BE CONTROLLED IN FAI.

△ PART NUMBER:
MDDR3-204XX10

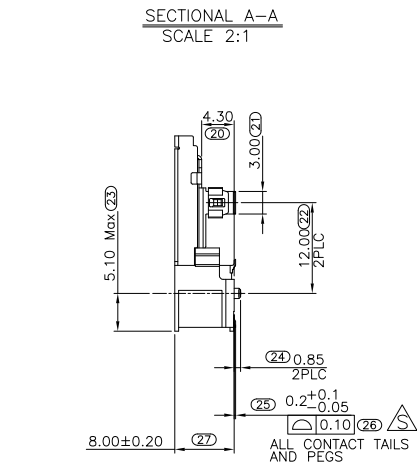
Series number

PLATING CODE:
1: GOLD FLASH 4: Au15u"
2: Au5u" 5: Au20u"
3: Au10u" 6: Au30u"

MARK & HSG COLOR:
0: DDR3 STD 1.5V & BLACK
1: DDR3 STD & BLACK 2: STD & BLACK
3: DDR3 STD 1.5V & IVORY
4: DDR3 STD & IVORY 5: STD & IVORY

PIN NUMBER CODE:
204: 204 PINS

NO	VARIETY	QTY	METERIAL	REMARK
Matrix Electronics Co.,Ltd				
TOLERANCE: X:X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR3 SO DIMM 8.0H STD ASSY
		CHECKED BY: Vicky Hsieh	DATE : 2015/11/02	PART NO. MDDR3-204XX10
		APPROVED BY1: Richard Hsieh	DATE : 2015/11/02	MOLD NO. NA
		APPROVED BY2: Richard Hsieh	DATE : 2015/11/02	DRAW NO.
UNIT: mm [inch]				SHEET NO. 1 OF 2
SCALE:1:1 SIZE:A4				



Series number

PLATING CODE:

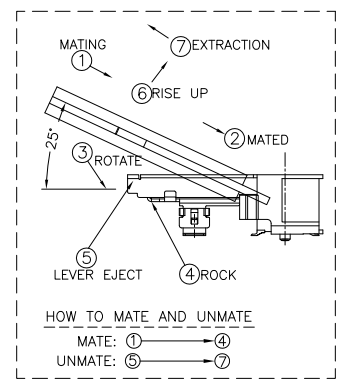
1: GOLD FLASH 4: Au15u”
2: Au5u” 5: Au20u”
3: Au10u” 6: Au30u”

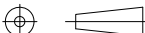
MARK & HSG COLOR:

0: DDR3 STD 1.5V & BLACK
1: DDR3 STD & BLACK 2: STD & BLACK
3: DDR3 STD 1.5V & IVORY
4: DDR3 STD & IVORY 5: STD & IVORY

PIN NUMBER CODE:

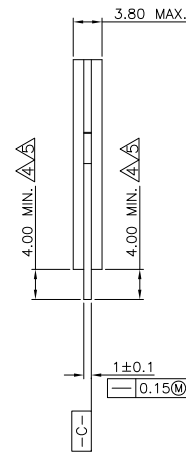
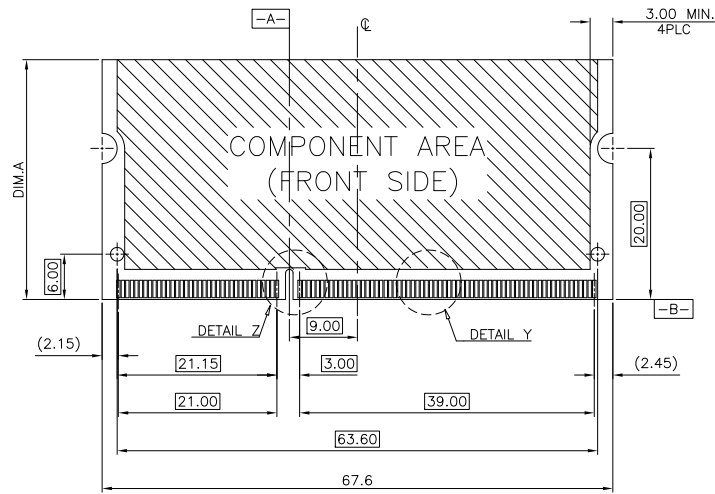
204: 204 PINS



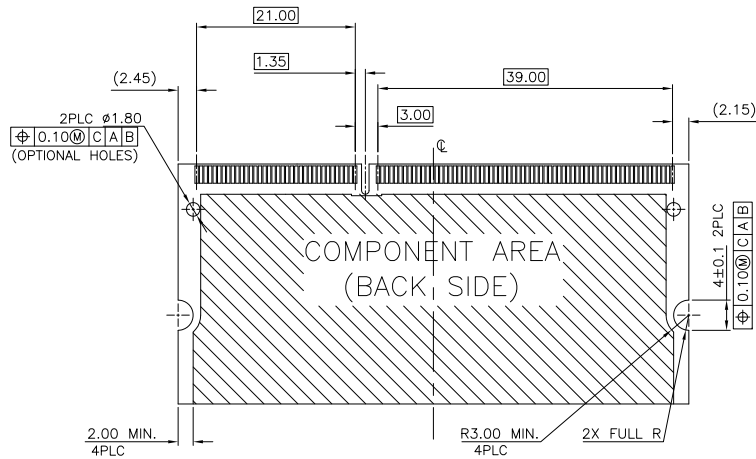
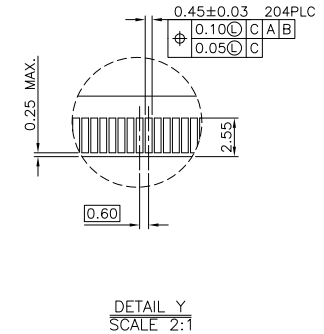
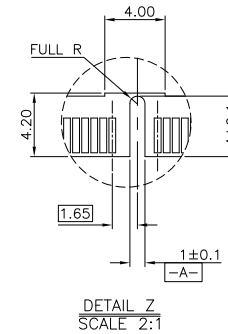
NO	VARIETY	QTY	MATERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X: X:X X:XX X:XXX ANGLE:		DESIGN BY : Phebe Su CHECKED BY: Vicky Hsieh APPROVED BY1: Richard Hsieh APPROVED BY2: Richard Hsieh		DATE : 2015/11/02 DATE : 2015/11/02 DATE : 2015/11/02 DATE : 2015/11/02	
				PART NAME: DDR3 SO DIMM 8.0H STD ASSY PART NO. MDDR3-204XX10 MOLD NO. NA DRAW NO. SHEET NO. 1 OF 2	
UNIT: mm [inch]					
SCALE:1:1	SIZE:A4				

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2015/11/02	Phebe Su



- NOTE:
1. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
 2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR MENTAIZATION.
 3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER Ni PLATING 0.002MIN.
 4. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE. PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.
 5. BORDER OF COMPONENT AREA.
 6. REFER TO JEDEC SPEC. MO-268 FOR COMPLETE MODULE.



RECOMMENDED MATING P.C.B CONFIGURATION

30.00	CA
31.75	BA
25.40	AA
DIM. A	SDRAM VARIATIONS

NO	VARIETY	QTY	METERIAL	REMARK
Matrix Electronics Co.,Ltd				
TOLERANCE:		DESIGN BY :	DATE :	PART NAME:
X:X ± 0.25		Phebe Su	2015/11/02	DDR3 SO DIMM 8.0H STD ASSY
X:XX ± 0.15		CHECKED BY:	DATE :	PART NO.
X:XXX ± 0.10		Vicky Hsieh	2015/11/02	MDDR3-204XX10
ANGLE: $\pm 3^\circ$		APPROVED BY1:	DATE :	MOLD NO.
		Richard Hsieh	2015/11/02	NA
UNIT: mm [inch]		APPROVED BY2:	DATE :	DRAW NO.
SCALE:1:1 SIZE:A4		Richard Hsieh	2015/11/02	SHEET NO.
				2 OF 2